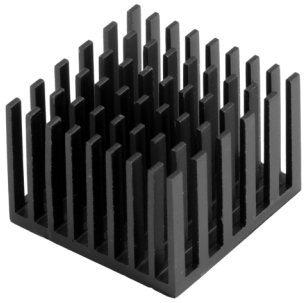
MODEL: HSB09-212115 | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- top mount
- aluminum alloy
- black anodized finish



RoHS

MODEL

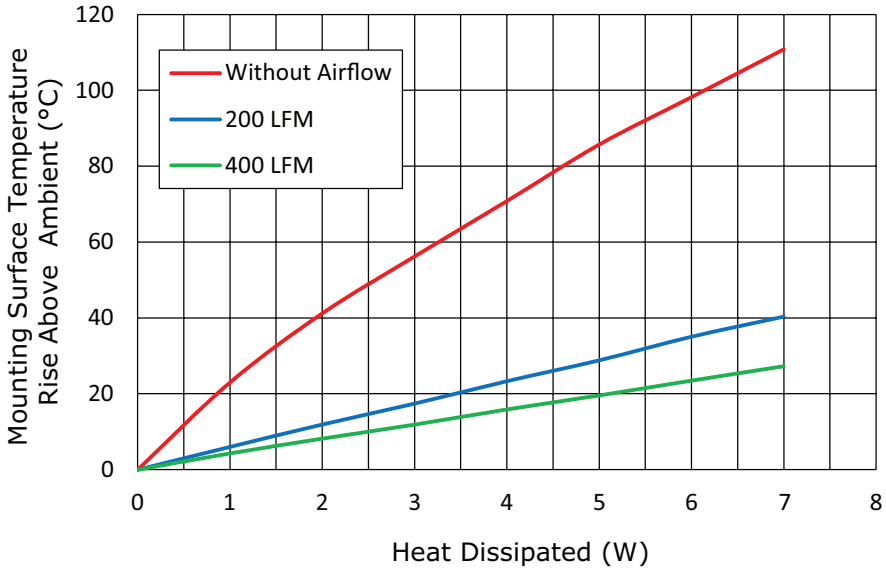
MODEL	thermal resistance[1] @ 75°C ΔT, nat conv (°C/W)	thermal resistance[1] @ 1 W, nat conv (°C/W)	thermal resistance[1] @ 1 W, 200 LFM (°C/W)	thermal resistance[1] @ 1 W, 400 LFM (°C/W)	power dissipation[1] @ 75°C ΔT, nat conv (W)
HSB09-212115	17.39	23.0	6.0	4.3	4.31

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	23.0	6.0	4.3
2	41.2	11.9	8.2
3	56.2	17.4	11.9
4	70.8	23.3	15.9
5	85.7	28.8	19.6
6	98.2	35.0	23.5
7	110.8	40.3	27.3

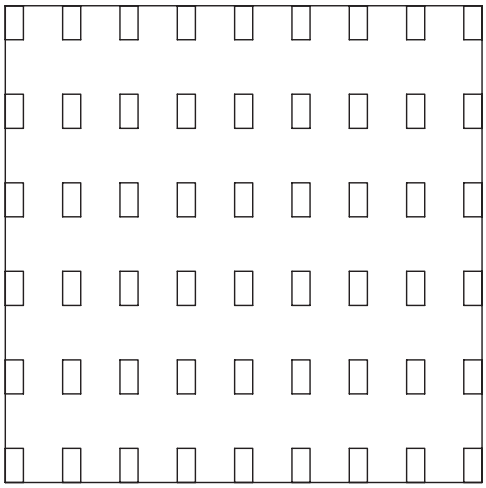
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature

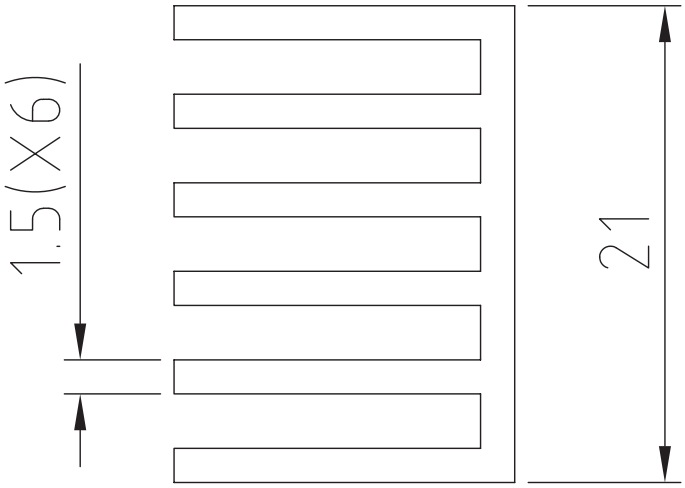


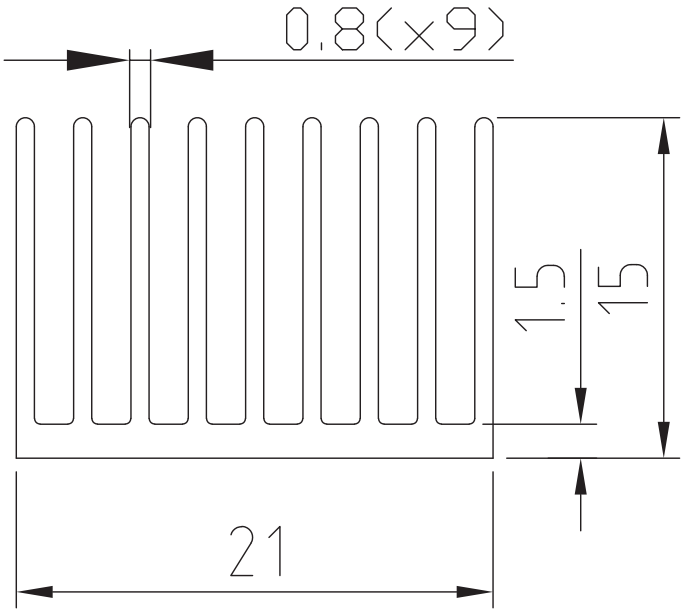
MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	10.1 g







REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.

CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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